

# 3.2x1.6 x0.8mm Chip LED

## **OSXX1206C1E**

### **■Features**

- Single chip
- Super high brightness of surface mount LED
- Compact package outline
   (L x W x T) of 3.2mm x 1.6mm x 0.8mm
- Compatible to IR reflow soldering.

# Cathode 3.2±0.2 Top Back 1. Cathode 2. Anode Unit:mm Tolerance:±0.20mm For reflow soldering(Propose) unless otherwise noted

**■Outline Dimension** 

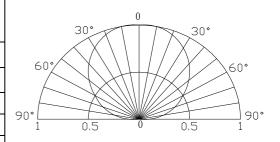
## Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

# ■Absolute Maximum Rating

Item	Cromb of	Val	Unit		
nem	Symbol	W5/M5/B5/G5	G8/Y5//O5/R5	Unit	
DC Forward Current	$I_{\mathrm{F}}$	30	30	mA	
Pulse Forward Current*	${ m I}_{ m FP}$	100	100	mA	
Reverse Voltage	$V_R$	5	5	V	
Power Dissipation	$P_D$	108	78	mW	
Operating Temperature	Topr	-40 ~ +85			
Storage Temperature	Tstg	-40~ +85			
Lead Soldering Temperature	Tsol	260°C/10sec			

# **■**Directivity



# **■**Electrical -Optical Characteristics

## (Ta=25°C)

			$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)				
Part Number	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
			I <sub>F</sub> =20mA		V <sub>R</sub> =5V	I <sub>F</sub> =20mA								
OSW51206C1E	White	W5		3.0	-	3.6	10	400	450	-	X=0.29 Y=0.29		120	
OSM51206C1E	Warm White	M5		3.0	-	3.6	10	400	450	-	X:0.44, Y:0.41		120	
OSB51206C1E	Blue	В5		3.0	-	3.6	10	80	100	-	460	465	475	120
OSG51206C1E	True Green	G5		2.9	-	3.6	10	300	350	-	520	525	530	120
OSG81206C1E	Yellow Green	G8		1.8	-	2.6	10	20	45	-	565	570	575	120
OSY51206C1E	Yellow	Y5		1.8	-	2.6	10	60	90	-	585	590	595	120
OSO51206C1E	Orange	O5		1.8	-	2.6	10	100	120	-	600	605	610	120
OSR51206C1E	Red	R5		1.8	-	2.6	10	100	120	-	620	625	630	120

<sup>\*1</sup> Tolerance of measurements of chromaticity coordinate is ±10%

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<sup>\*</sup>Pulse width Max 0.1ms, Duty ratio max 1/10

<sup>\*2</sup> Tolerance of measurements of dominant wavelength is ±1nm

<sup>\*3</sup> Tolerance of measurements of luminous intensity is ±15%

<sup>\*4</sup> Tolerance of measurements of forward voltage is  $\pm 0.1 V$ 



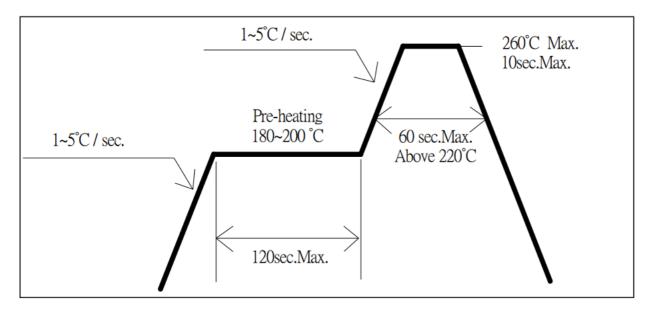
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### **■ Soldering Conditions**

	Reflow Soldering	Hand Soldering				
Pre-Heat	180 ~ 200°C					
Pre-Heat Time	120 sec. Max.					
Peak temperature	260°C Max.	Temperature	350°C Max.			
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.			
Condition	Refer to Temperature-profile		(one time only)			

### • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

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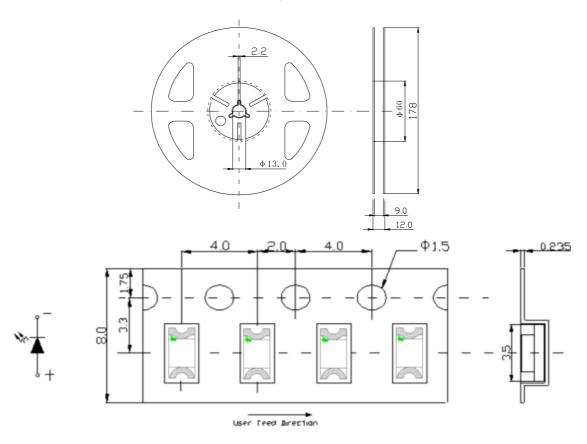


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# ■ Taping and Orientation.

- 1. Quantity:3000pcs/Reel
- 2. Note: The tolerances unless mentioned is ±0.1mm,Unit:mm



#### **■ Cautions:**

- 1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. ( The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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